

(0,80 mm) .0315"

BTE, BSE SERIES

BASIC BLADE & BEAM HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTE or www.samtec.com?BSE

Insulator Material: Liquid Crystal Polymer
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Current Rating: 2 A per pin (1 pin powered per row)
Operating Temp Range: -55°C to +125°C
Voltage Rating: 225 VAC with 5 mm Stack Height
Max Cycles: 100
RoHS Compliant: Yes

Processing:
Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10 mm) .004" max (020-080) (0,15 mm) .006" max (100-120)
Board Stacking:
 For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5,00) .197
-02	(8,00) .315

*Processing conditions will affect mated height.

ALSO AVAILABLE (MOQ Required)

- 30µ" (0,76 µm) Gold
 - Edge Mount Capability
 - Friction Lock option
 - 11 mm, 14 mm, 16,10 mm, 19,10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

BTE

Mates with:
BSE

NO. OF POSITIONS PER ROW

-020, -040, -060, -080, -100, -120

LEAD STYLE

Specify LEAD STYLE from chart

PLATING OPTION

-F
= Gold Flash on contact, Matte Tin on tail

-L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-C*
= Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

D

A

OTHER OPTION

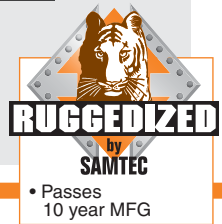
-K
= (7,00 mm) .275" DIA Polyimide Film Pick & Place Pad

-TR
= Tape & Reel (60 positions maximum)

No. of positions x (0,80) .0315 + (4,00) .1575

LEAD STYLE	A
-01	(4,27) .168
-02	(7,21) .284

***Note:** -C Plating passes 10 year MFG testing



BSE

Mates with:
BTE

NO. OF POSITIONS PER ROW

-020, -040, -060, -080, -100, -120

01

PLATING OPTION

-F
= Gold Flash on contact, Matte Tin on tail

-L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-C*
= Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

D

A

OTHER OPTION

-TR
= Tape & Reel (80 positions maximum)

No. of positions x (0,80) .0315 + (5,27) .2075

***Note:** -C Plating passes 10 year MFG testing